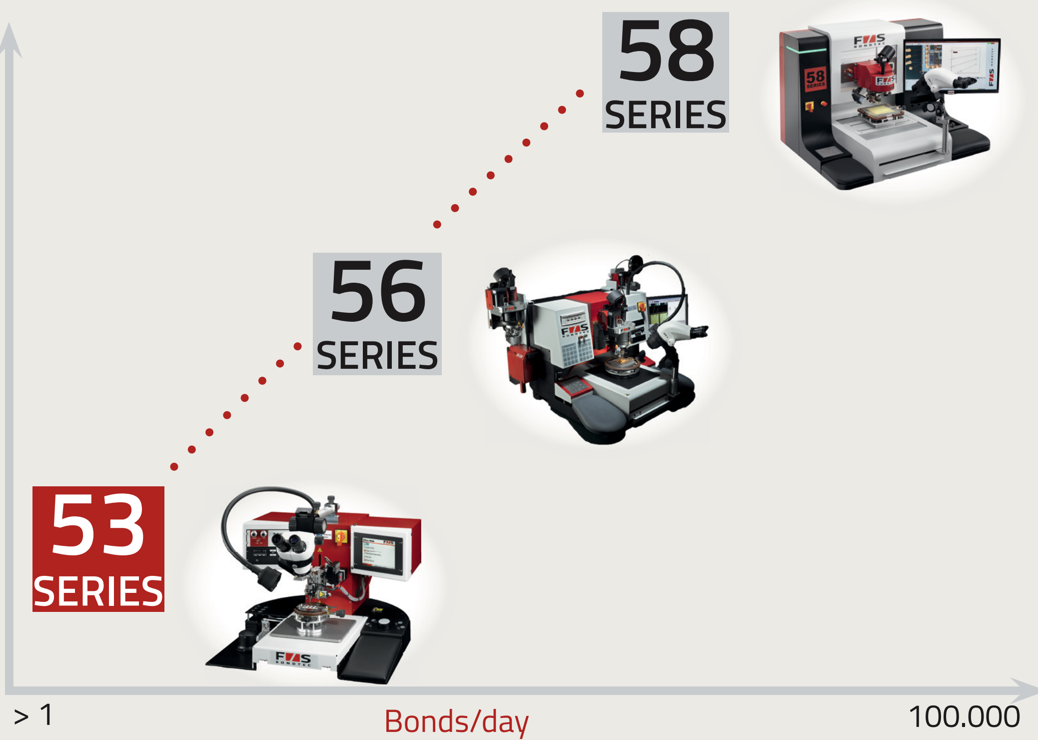

D. Seidl 2015 vers. 1

TECHNOLOGY	SERIES 53	SERIES 56	SERIES 58
GOLD-BALL	5310, 53xx BDA	5610	5810
THIN WIRE WEDGE-WEDGE	5330	5630	5830
THIN WIRE DEEP ACCESS	53xx BDA	5632	5832
HEAVY WIRE	5350	5650	5850
HEAVY RIBBON	5350 HR	5650 HR	5850 HR

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BONDiNG THE STARS

SERIES 53
SMALL. MANUAL. EASY.

ENGLISH

BONDiNG THE STARS

SERIES 53
The Development Machine

You need: 1 up to 1000 BONDS PER DAY

>> In-house production to protect your technology and to provide short Time-to-Market
>> Wirebonder for small production volumes; high quality requirements
>> High mix / low volume; frequent product changes; small volumes
>> Reproduceable Bonding results
>> Repair works or R&D

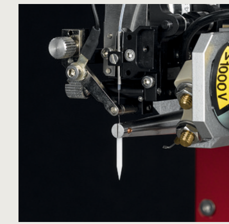
THE SOLUTION: SERIES 53

53 SERIES

>> Complete, manual table top bonder
>> Unbeatable price-to-performance ratio
>> Extremely adaptable bond settings, loop shapes, force and power profiles etc.
>> Dual wire clamp system for reproduceable loop and tails
>> Easy handling

BONDHEADS

F/S BONDTEC

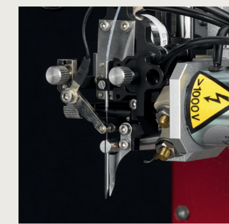


5310 – Gold-Ball

>> Gold-Ball-Bonding for wires from 17,5 to 50 µm using Standard-Capillaries 16 mm to 19 mm
>> Dual frequency-US-generator for 60/100 kHz further Bondfrequencies available on request
>> Bumping, Safety-Bump, Stitch-on-Ball
>> Programmable Z-Axis 60mm

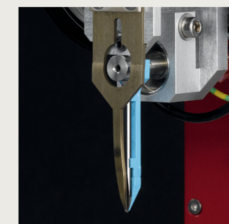
5330 – Thin wire Wedge-Wedge

>> Wedge-Wedge-Bonding with 1“ Tools for Aluminum- and Goldwires from 17,5 to 75 µm and ribbon up to 250x25µ
>> 45° wireguide, retrofitable to 30° and 60° – according to component geometry
>> Dual frequency-US-generator for 60/100 kHz further Bondfrequencies available on request
>> Programmable Z-Axis 60mm and Y-Axis 25mm



53xx BDA – Ball-DeepAccess

>> Wedge-Wedge-Bonding with 1“ or ¾“ Tools
>> 90° wireguide for Aluminum- and Goldwires from 17,5 to 75 µm
>> Gold-Ball-Bonding for wires from 17,5 to 50 µm with capillaries 16 -19 mm
>> Perfect for difficult and constricted bonding geometries
>> Also useable for ribbon of aluminum und gold
>> Programmable Z-Axis 60mm and Y-Axis 25mm
>> optional: retrofitable to 5380 DIE-Bonder

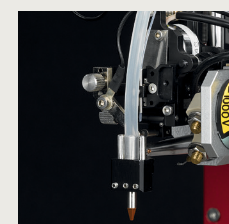


5350 – Heavy-Wire

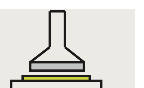
>> Wedge-Wedge-Bonding for aluminum heavy wire from 100 to 500 µm diameter // copper from 100 to 300 µm
>> Wedge-Tool length from 50 to 70 mm also for extreme bonding requirements
>> Stitch- or chain bonds of any length
>> Clip-on-wire guide for quick exchange
>> Optional: retrofitable to 5350 HR heavy ribbon bondhead
>> Programmable Z-Axis 60mm and Y-Axis 25mm

5350 HR– Heavy Ribbon

>> Wedge-wedge bonding for heavy aluminum or copper ribbons up to 2mm width
>> Increased programmable bond force up to 6,000 cN, also with force and power ramps
>> Active ribbon guide to improve loop shaping
>> Programmable Z-Axis 60mm and Y-Axis 25mm



5380 – optional: DIE-Bonder



>> Different DIE-sizes process oriented useable
>> manual DIE-bonding with Touchdown-Detection and programmable pickup- and bond force
>> 2x2“ working area for any Waffle-, Gel-Packs or Trays
>> Bond- and pickup force from 5 up to 500 cN programmable